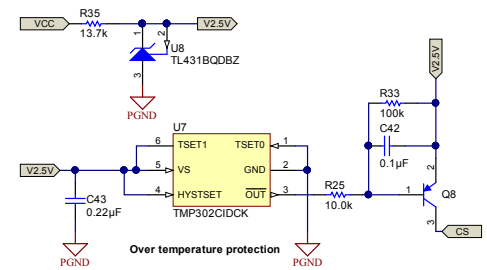


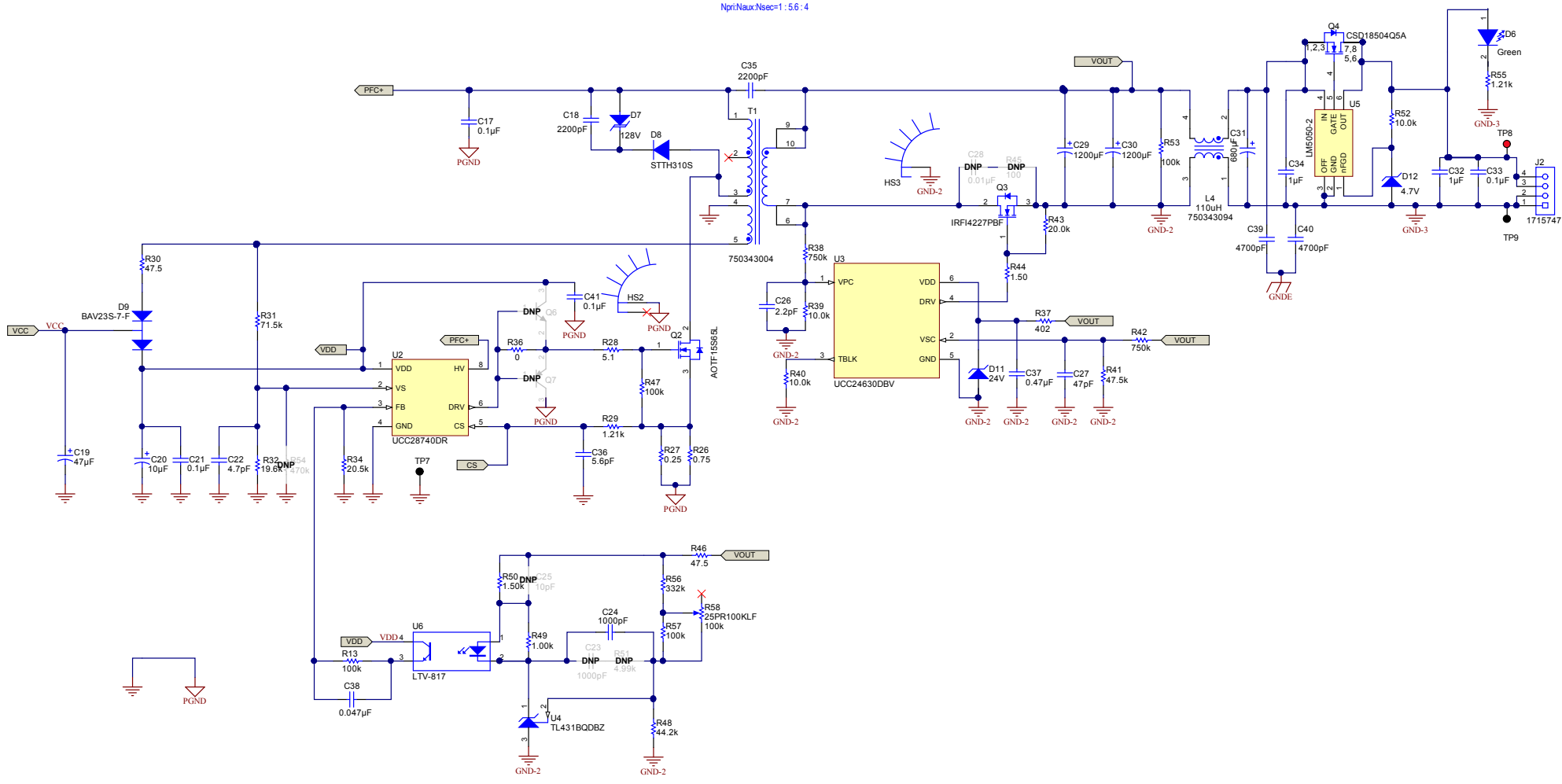
Boost Follower Setting



Over temperature protection

NOTES:
 For Boost Follower Configuration:
 Populate R21, R45 and Q5 and set R9 = 10.5k
 Change R1 to 0.33 Ohm
 For Fixed Output Boost PFC configuration
 Do not populate R21 and Q5 and Set R9 = 6.49k
 Populate R1 = 0.3 Ohm

Npri:Naux:Nsec=1:56:4



Mounting Accessories for Board



Mounting Accessories for Heatsinks HS1, HS2 & HS3



M1, M2, M3 are NOT needed when TO-220-Flatpack package is used



PCB Number: TIDA-00701
PCB Rev: RevB

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

You should delete the nylon screws/standoffs and/or the bump-ons as needed for your design (or substitute other parts from Hardware.IntLib). Bump-ons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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